

Electronic Patent Application Fee Transmittal

Application Number:	10715641			
Filing Date:	18-Nov-2003			
Title of Invention:	RAISED SOLDER-MASK-DEFINED (SMD) SOLDER BALL PADS FOR A LAMINATE ELECTRONIC CIRCUIT BOARD			
First Named Inventor/Applicant Name:	Tz-Cheng Chiu			
Filer:	Wade J. Brady III/Jackie McBride			
Attorney Docket Number:	TI-36052			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Certificate of correction	1811	1	100	100
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				100